399-100A-305670
Ball Grid Array Circuit Bridge

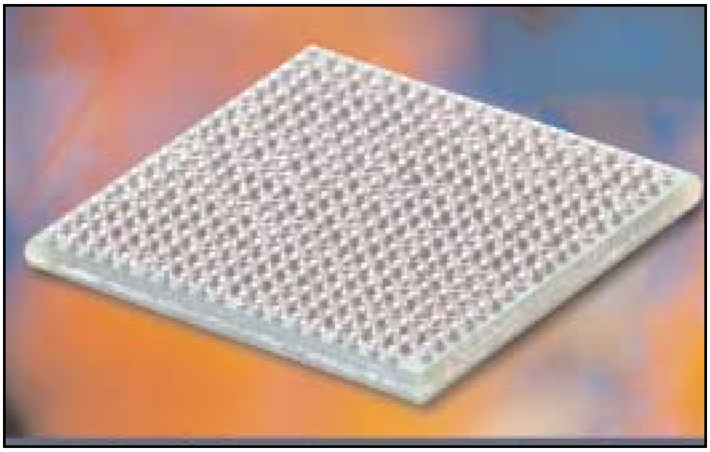
FEATURES:
- A cost effective means of upgrading or testing without changing your PCB layout.

SPECIFICATIONS:
- Board Material is .062 thick FR-4 with 10 layers.
- Solder Balls are .020 dia Sn/Pb 90/10.
- Operating temperature = 221ºF [105ºC]

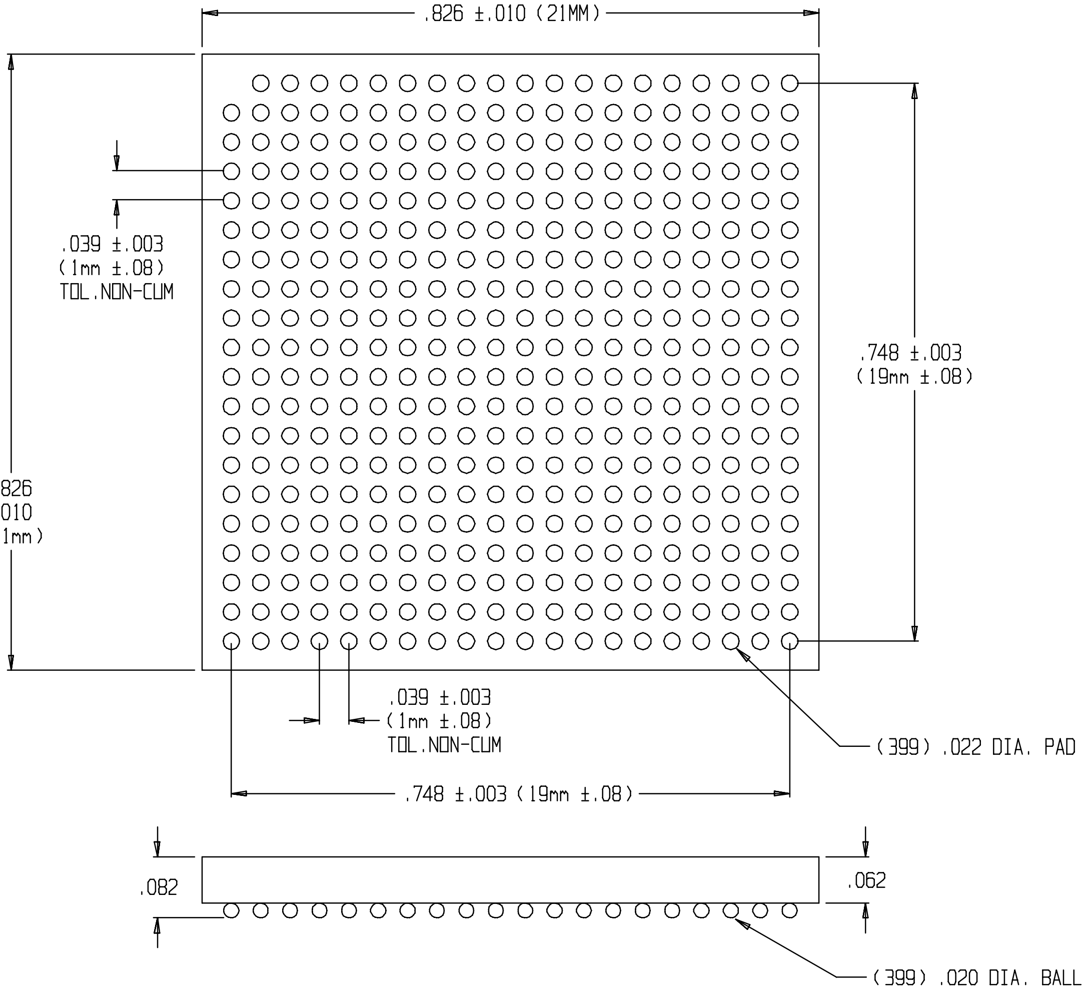
MOUNTING CONSIDERATIONS:
- Suggested PCB pad size = .028± .022 dia.

ALL DIMENSIONS: INCHES

All toleranaces ± .005 [.13]
unless otherwise specified



Note: Aries specializes in custom design and production. In addition to the standard products shown on this page, special materials, platings, sizes, and configurations can be furnished, depending on quantities. Aries reserves the right to change product specifications without notice.



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